

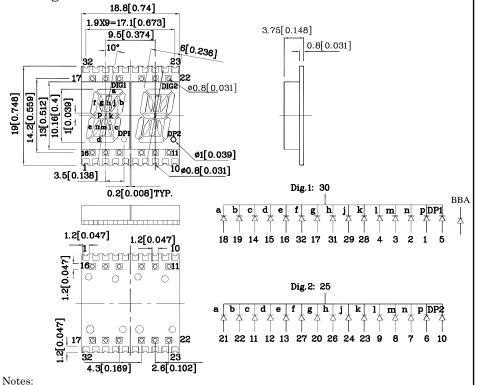
SURFACE MOUNT DISPLAY

Package Schematics

Features

- $\bullet~0.4$ inch digit height
- \bullet Robust package
- Low power consumption
- Standard configuration: Gray face w/ white segments
- Standard Package: 250pcs/ Reel
- MSL (Moisture Sensitivity Level): 2a
- RoHS Compliant







ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE

DEVICES

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01")$ unless otherwise noted. 2. Specifications are subject to change without notice.

3. The gap between the reflector and PCB shall not exceed 0.25mm.

Absolute Maximum Ratings (T _A =25°C)		BBA (InGaN)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	$I_{\rm F}$	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	100	mA	
Power Dissipation	P_{D}	120	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	$-40 \sim +85$		
Electrostatic Discharge Threshold (HBM)		1000	V	

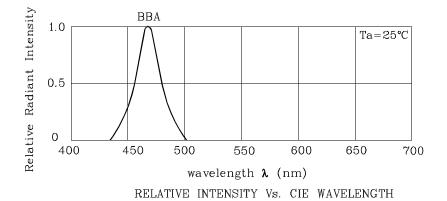
Operating Characteristics (T _A =25°C)		BBA (InGaN)	Unit
Forward Voltage (Typ.) (I _F =10mA)	3.05	V	
Forward Voltage (Max.) (I _F =10mA)	V_{F}	4	V
Reverse Current (Max.) (V_R =5V)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λP	468*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λD	465*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$ riangle\lambda$	21	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	100	pF

Part Number	Emitting Color	Emitting Material	Luminous Int CIE127-20 (I _F =10mA ucd	007*	Wavelength CIE127-2007* nm λP	Description
			min.	typ.		
XZFABBA10C2	Blue	InGaN	2200* 5	5790*	468*	Common Cathode, Rt. Hand Decimal

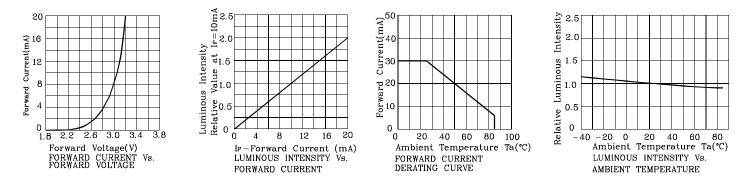
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards. Jan 15.2014

XDSB1625 V3-Z Layout: Maggie L.





✤ BBA



LED is recommended for reflow soldering and soldering profile is shown below.

300 (°C) 10 s max iner? 250 4°C/s C/s max 200 150~180 4°C/s max 150 Temperature 30~50s 60~120: 100 50 0

Reflow Soldering Profile for SMD Products (Pb-Free Components)

1. Maximum soldering temperature should not exceed 260°C

150

200

250

300 (sec)

2. Recommended reflow temperature: 145°C-260°C 3. Do not put stress to the epoxy resin during

Time

high temperatures conditions

100

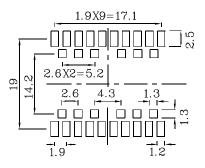
50

0

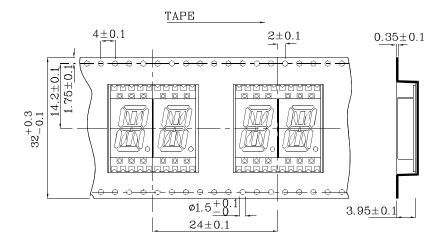
Notes:



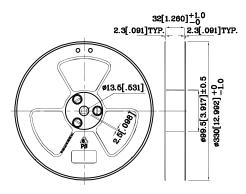
& Recommended Soldering Pattern (Units : mm; Tolerance: ±0.15)



Tape Specification (Units : mm)



Reel Dimension



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

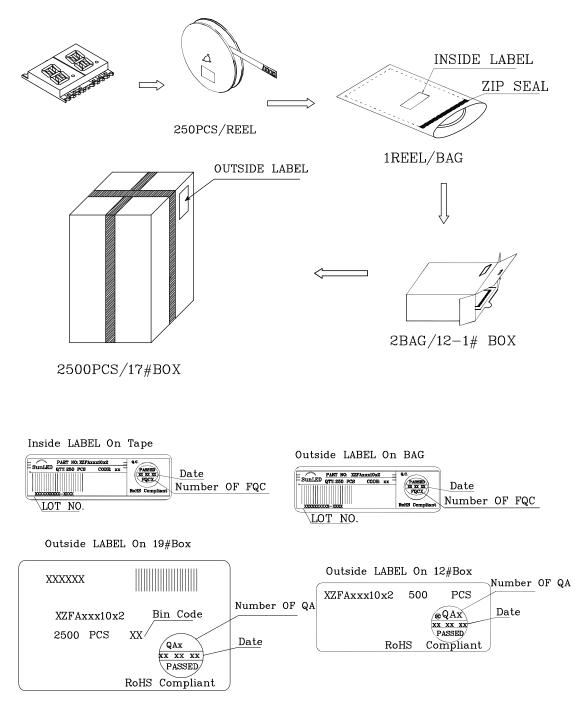
2. Luminous intensity / luminous flux: +/-15\%

3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
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- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp